

# MA2YF800G

Silicon epitaxial planar type

For high speed switching circuits  
For strobe light circuits (high voltage rectification)

■ Features

- High repetitive peak reverse voltage  $V_{RRM}$
- Short reverse recovery time  $t_{rr}$

■ Absolute Maximum Ratings  $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	$V_{RRM}$	800	V
Non-repetitive peak reverse surge voltage	$V_{RSM}$	800	V
Forward current	$I_F$	200	mA
Non-repetitive peak forward surge current *	$I_{FSM}$	1	A
Junction temperature	$T_j$	-40 to +150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +150	$^\circ\text{C}$

Note) \*: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Package

- Code  
Mini2-F2
- Pin Name  
1: Anode  
2: Cathode

■ Marking Symbol: HB

■ Internal Connection

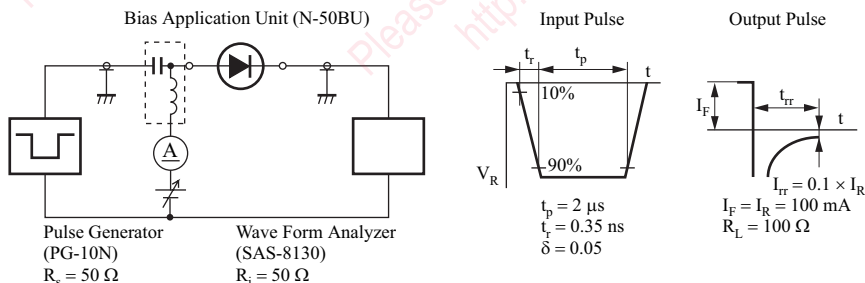


■ Electrical Characteristics  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 200 \text{ mA}$			2.5	V
Reverse current	$I_{RRM1}$	$V_{RRM} = 400 \text{ V}$			1	$\mu\text{A}$
	$I_{RRM2}$	$V_{RRM} = 800 \text{ V}$			20	
Terminal capacitance	$C_t$	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		2		pF
Reverse recovery time *	$t_{rr}$	$I_F = 100 \text{ mA}, I_R = 200 \text{ mA}$ $I_{rr} = 20 \text{ mA}, R_L = 100 \Omega$		20	45	ns

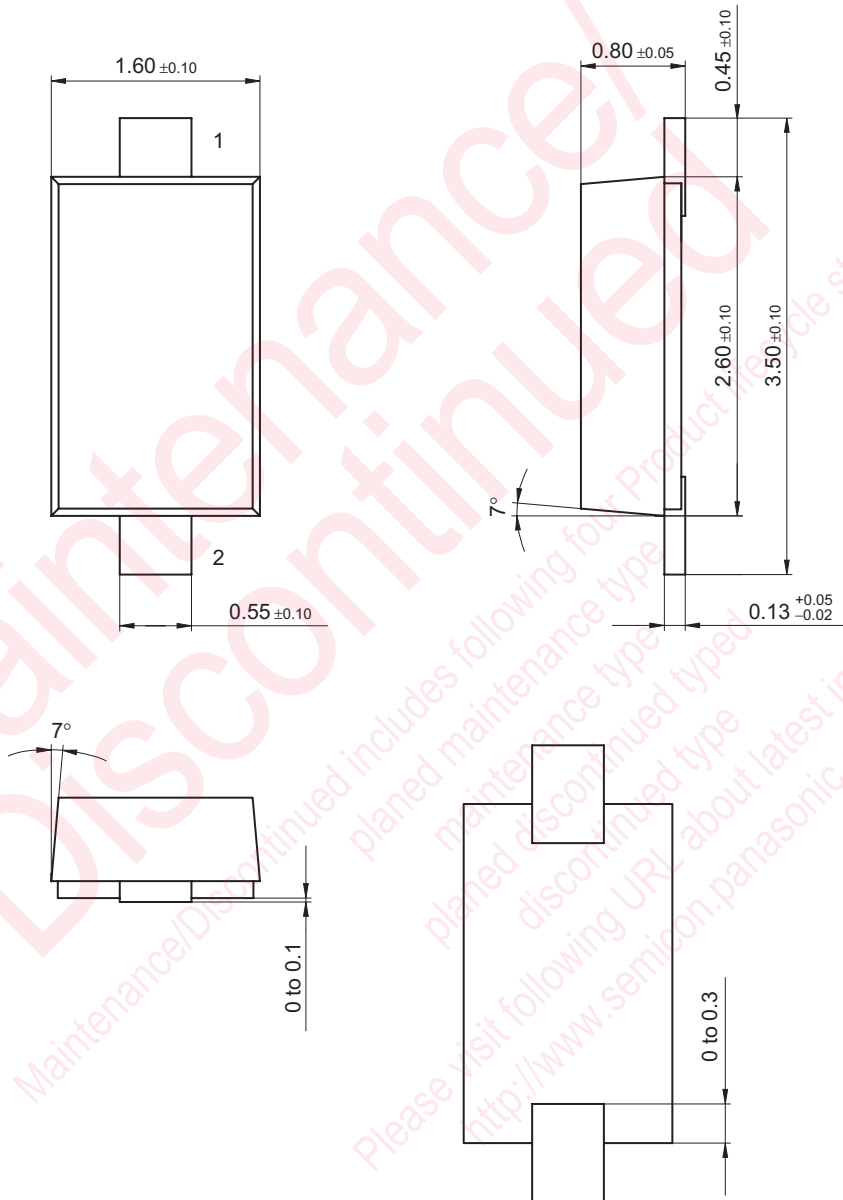
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. \*:  $t_{rr}$  measurement circuit



Mini2-F2

Unit: mm



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